

ELECTRICAL AND TEMPERATURE
CHARACTERISATION OF SILICON AND
GERMANIUM NANOWIRE TRANSISTORS
BASED ON CHANNEL DIMENSIONS

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ABSTRAK

Antara pelbagai teknik, pengesanan berdasarkan transistor kesan medan (FET) telah menarik perhatian pihak industri dan akademik. Disebabkan ciri-ciri unik seperti saiz yang kecil, ringan, murah, fleksibiliti, pantas respon, stabil, dan keupayaan untuk menurun skala, nanowire transistor (NWTs) boleh berfungsi sebagai pengesan nano yang ideal. Mereka adalah peneraju untuk peranti nano berasaskan FET. Oleh kerana dimensi (panjang, diameter dan ketebalan oksida) saluran NWT berkurangan, ciri elektrik dan suhu NWTs terjejas dan merendahkan prestasi. Walaupun penggunaan NWTs sebagai pengesan biologi atau kimia diterokai secara meluas, kurang penekanan transistor tersebut sebagai pengesan suhu. Maka, penyelidikan ini bertujuan untuk menyasat kesan dimensi keratan rentas Silikon Nanowire Transistor (SiNWT) dan Germanium Nanowire Transistor (GeNWT) terhadap ciri elektrik dan suhu mereka. Seterusnya menilai dan membandingkan prestasi nanowires dan kebolehgunaannya sebagai pengesan suhu nano untuk pemantauan suhu berterusan dengan keupayaan pengesanan yang unggul, tinggi fleksibiliti dan rendah kos. Kajian perbandingan berasaskan simulasi dijalankan bergantung pada Enam parameter, iaitu panjang get (L_g), diameter saluran (D_{ch}), ketebalan oksida (T_{ox}), suhu persekitaran (T), Voltan pincang get (V_g), dan voltan pincang salir (V_{DD}). Kesan mengubah parameter yang dinyatakan pada prestasi SiNWT dan GeNWT dinilai berdasarkan ciri elektrik dan suhu. Alat simulasi MuGFET untuk struktur FET pelbagai get skala nano digunakan untuk menjalankan simulasi dengan syarat tertentu. Pelbagai parameter disimulasikan dalam Tiga senario simulasi utama termasuk 21 voltan operasi dan peningkatan suhu persekitaran dari 225 ke 450 K dengan langkauan 25 K. Senario pertama menguji variasi panjang get ($L_g = 25, 45, 65, 85$ dan 105 nm), manakala senario kedua memberi tumpuan kepada variasi diameter saluran ($D_{ch} = 10, 20, 40$ dan 80 nm) dan yang terakhir membezakan ketebalan saluran oksida ($T_{ox} = 1, 2, 3, 4$ dan 5 nm). Empat metrik penilaian digunakan termasuk Subthreshold Swing (SS), Voltan ambang (V_{th}), Induksi Salir Penghalang Rendah (DIBL) dan kadar variasi arus saluran, ΔI_d sebagai penunjuk kepekaan suhu. Kebiasaannya, prestasi terbaik NWTs boleh dicapai pada voltan operasi optimum dengan nilai SS lebih dekat keadaan ideal, tahap DIBL rendah dan nilai voltan ambang tinggi. Hasil simulasi SiNWT dan GeNWT menunjukkan kesan dimensi saluran berbeza (L_g, D_{ch}, T_{ox}) pada suhu dan ciri-ciri elektrik. Kepekaan suhu (ΔI_d) telah meningkat dengan meningkatkan pelbagai dimensi saluran dan suhu operasi untuk kedua-dua SiNWT dan GeNWT dan voltan operasi optimum telah dikenalpasti bagi setiap NWT. SiNWT menunjukkan lebih kestabilan dalam variasi suhu persekitaran berbanding GeNWT yang stabil dalam semua senario. SiNWT juga mengatasi GeNWT dari segi SS dan V_{th} , maka ia dapat meningkatkan kelajuan pensuisan dan mengurangkan kebocoran arus kerana SS sangat dekat dengan keadaan ideal dan voltan ambang adalah tinggi berbanding dengan GeNWT. SiNWT mencapai tahap DIBL yang lebih tinggi dalam kes tertentu, tetapi ia boleh diterima untuk kebanyakan dimensi saluran. Kesan perubahan panjang get adalah sangat jelas pada operasi NWTs dan impak terendah dapat dilihat dari pelbagai ketebalan oksida. SiNWT mempunyai lebih kebolehgunaan sebagai pengesan suhu nano kerana kestabilan ciri elektrik dan suhunya.

ABSTRACT

Amongst various sensing and monitoring technologies, sensors based on field effect transistors (FETs) have attracted considerable attention from both the industry and academia. Owing to their unique characteristics such as their small size, lightweight, low cost, flexibility, fast response, stability and ability for further downscaling, nanowire transistors (NWTs) can serve as ideal nanosensors and successors to FET-based nanoscale devices. However, as the dimensions (length, diameter and oxide thickness) of NWT channels are shrinking down, the electrical and temperature characteristics of NWTs are affected, thereby degrading the transistor performance. Although the applications of NWTs as biological and/or chemical sensors have been extensively explored in the literature, the use of these transistors as temperature sensors has been largely ignored. Consequently, this research investigates the impact of the cross-sectional dimensions of silicon nanowire transistors (SiNWTs) and germanium nanowire transistors (GeNWTs) on their electrical and temperature characteristics. Accordingly, evaluate and compare the performance of the considered nanowires and their potential applicability as temperature nanosensors for continuous temperature monitoring with good detection capability, high flexibility and low cost. A comprehensive simulation-based comparative study is performed by using six variable parameters, namely, gate length (L_g), channel diameter (D_{ch}), oxide thickness (T_{ox}), ambient temperature (T), gate bias voltage (V_g) and drain bias voltage (V_{DD}). The impact of changes in these parameters on the electrical and temperature characteristics of SiNWTs and GeNWTs is then evaluated. The well-known MuGFET simulation tool for nanoscale multi-gate FET structure is used for the experimental simulations. A wide range of variable parameters are simulated in three simulation-based case studies, which cover 21 operating voltages and an ambient temperature increasing from 225 K to 450 K by a step of 25 K. The first case study considers the variation in gate length ($L_g = 25, 45, 65, 85$ and 105 nm), the second focuses on the variation in channel diameter ($D_{ch} = 10, 20, 40$ and 80 nm) and the third focuses on the variation in channel oxide thickness ($T_{ox} = 1, 2, 3, 4$ and 5 nm). Four performance evaluation metrics are considered, namely, subthreshold swing (SS), threshold voltage (V_{th}), drain-induced barrier lowering (DIBL) and drain current variation rate, ΔI_d , which serves as an indicator of temperature sensitivity. The optimal stability- and sensitivity-based performance of NWTs can be achieved at certain optimal operating voltages with the SS values closer to the ideal state, a lower DIBL level and higher voltage threshold values. The simulation results for SiNWTs and GeNWTs highlight the effects of varying the channel dimensions (L_g , D_{ch} , and T_{ox}) on their temperature and electrical characteristics. Specifically, the temperature sensitivity (ΔI_d) of SiNWTs and GeNWTs significantly increased along with various channel dimensions and operating temperatures, and the optimal operating voltages are identified for each NWT. According to their temperature characteristics, SiNWTs show higher stability to ambient temperature variations compared with GeNWTs, which in turn demonstrate a higher sensitivity in all cases compared with SiNWT. In addition, SiNWTs outperform GeNWTs in terms of SS and V_{th} and demonstrate a faster switching speed and lower leakage current given that the values of SS are very close to the ideal state and high threshold voltages. SiNWTs also achieve a high DIBL level in certain cases, which is considered acceptable for most channel dimensions. The impact of changing the gate length on the behaviour of NWTs is very obvious, and varying the oxide thickness demonstrates the lowest impact. SiNWTs have high potential to be applied as temperature nanosensors due to their electrical and temperature stability.

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LIST OF SYMBOLS

C	Capacitors
I	Current
I-V	Current-voltage
V_{DD}	Drain DC voltage source
I_{ds}	Drain to source current
I_d	Drain current
V_{DS}	Drain to source voltage
V_g	Gate voltage
V_{GS}	Gate to source voltage
I_{OFF}	OFF current
I_{ON}	ON current
R_{out}	Transistor resistance
T	Temperature
V	Voltage

LIST OF ABBREVIATIONS

AFM	Atomic Force Microscope
AM	Accumulation Mode
ABMS	Agent Based Modelling and Simulation
B ₂ H ₆	Diborane
BE	Ballistic Efficiency
Cal.Tech	California Institute of Technology
CVD	Chemical Vapour Deposition
CMOS	Complementary Metal Oxide Semiconductor
ρ_C	Contact Resistivity
di	Diode
DG-FET	Double-Gate Field-Effect Transistor
D _{ch}	Channel Diameter
DIBL	Drain Induced Barrier Lowering
EELS	Electron Energy Loss Spectroscopy
FinFET	Fin-Shaped Field Effect Transistor
GAA	Gate All Around
L _g	Gate Lengths
NMH	High-State Noise Margins
IC	Integrated Circuits
ITRS	International Technology Roadmap for Semiconductors
IGZO	Indium Gallium Zinc Oxide
IoT	Internet of Things
NML	Low-State Noise Margins
MOS diode	Metal Oxide Semiconductor Diode
MOSFET	Metal Oxide Semiconductor Field Effect Transistor
MuGFET	Multi Gate Field Effect Transistor
Ni-nGe	Nickle – Germanium N-Type
Nm	Nanometer
NO ₂	Nitrogen Dioxide
NW	Nanowire

NWT	Nanowire Transistor
NIST	National Institute of Standards and Technology
NNI	National Nanotechnology Initiative
NMOS	N-Channel Metal Oxide Semiconductor
NRs	Nanorods
PEDOT: PSS	Poly(3,4-Ethylenedioxythiophene) Polystyrene Sulfonate
PNWTs	Pentagonal
PH ₃	Phosphine
PN junction	P- Type and N- Type Junction
SEM	Scanning Electron Microscope
STM	Scanning Tunnelling Microscope
SCE	Short Channel Effect
SiNWFET	Silicon Nanowire Field Effect Transistor
SG	Single-Gate
R _{sh}	Sheet Resistance
SOI	Silicon On Insulator
SWCNT	Single-Walled Carbon Nanotube
SS	Sub Threshold Slope
T _{ox}	Oxide Thickness
TCAD	Technology Computer Aided Design
V _{th}	Threshold Voltage
TEM	Transmission Electron Microscope
TrNWTs	Trapezoidal
TLM	Transmission Length Model
VNWFET	Vertical Nanowire Field Effect Transistor
VLS	Vapour Liquid Solid
VLSI	Very Large Scale Integration
ZnO	Zinc Oxide

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